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ROHM Co., Ltd. ("ROHM"), on the 1st day of April, 2024,
has absorbed into merger with 100%-owned subsidiary of LAPIS Technology Co., Ltd.

Therefore, all references to "LAPIS Technology Co., Ltd.", "LAPIS Technology"
and/or "LAPIS" in this document shall be replaced with "ROHM Co., Ltd."

Furthermore, there are no changes to the documents relating to our products other than
the company name, the company trademark, logo, etc.

Thank you for your understanding.

ROHM Co., Ltd.
April 1, 2024

ML630Q464/Q466

Ultra Low Power 32-bit Microcontroller

■GENERAL DESCRIPTION

This LSI is a high-performance low power 32-bit microcontroller. Equipped with a 32-bit CPU core ARM®Cortex®-M0+, it implements a 128 KB flash memory* 16 KB RAM, rich peripheral circuits, such as USB Full speed device, synchronous serial port, UART, I²C bus interface, supply voltage level detect circuit, RC oscillation type A/D converter, successive approximation type A/D converter, and LCD driver. The Flash ROM* that is installed as program memory achieves low-voltage low-power consumption operation (read operation) is most suitable for battery-driven applications.

*: This product uses SuperFlash® technology licensed from Silicon Storage Technology, Inc. SuperFlash® is a registered trademark of Silicon Storage Technology, Inc.

• Applications

Consumer and Industrial equipment (e.g., Household appliances, Housing equipment, Office equipment, Measurement instrumentation, etc)

【NOTE】

This product cannot be applicable for automotive use, automatic train control systems, and railway safety systems.

Please contact ROHM sales office in advance if contemplating the integration of this product into applications that requires high reliability, such as transportation equipment for ships and railways, communication equipment for trunk lines, traffic signal equipment, power transmission systems, core systems for financial terminals and various safety control devices.

■FEATURES

• CPU

- 32-bit RISC CPU (CPU name: ARM®Cortex®-M0+)
- ARM®Thumb®/Thumb®-2 instruction supported
- Serial Wire Debug Port
- Minimum instruction execution time
 30.5 μs (@32.768 kHz system clock)
 41.7ns (@24 MHz system clock)

• Internal memory

- Re-writing the program memory area by software
- Number of segments

Product name	Flash memory		SRAM
	Program area	Data area	
ML630Q464	64KB (16K × 32bit)	2KB (0.5K × 32bit)	8KB (2K × 32bit)
ML630Q466	128KB (32K × 32bit)	2KB (0.5K × 32bit)	16KB (4K × 32bit)

• Interrupt controller (NVIC)

- 1 non-maskable interrupt source (Internal source: 1)
- 31 maskable interrupt sources (Internal sources: 30, External sources: 1)
- Priority level (4-level) can be set for each interrupt



- DMA controller (DMAC)
 - 2 channels
 - Enable to allocate multiple DMA transfer request sources for each channel.
 - Channel priority: fixed mode/round robin mode
 - DMA transfer mode: cycle steal mode/burst mode
 - DMA request type: software requests/hardware requests
 - Maximum transfer count: 65,536
 - Data transfer size: 8 bits/16 bits/32 bits
 - Transfer request source: SSIOF, UART, UARTF, I2CF, RC-ADC, SA-ADC
- Time base counter (TBC)
 - Low-speed time base counter ×1 channel
- 1 kHz Timer
 - 10 Hz / 1 Hz interrupt function
- Timers (TMR)
 - 8 bits × 8 channels
(Timer0-7: 16-bit x 4 configuration available by using Timer0-1 or Timer2-3, Timer4-5, Timer6-7)
 - Selection of one shot timer mode is possible
 - External clock can be selected as timer clock.
- Function Timers (FTM)
 - 16-bit × 4 channels
 - Equipped with the timer/capture/PWM functions using a 16-bit counter
 - An event trigger (external pin input interrupt or timer interrupt request) can control start/stop/clear of the timer (however, the minimum pulse width of pin input is timer clock 3φ)
 - 1 to 64 dividing of LSCLK/OSCLK/HSCLK/external input selectable as timer clock
 - Two types of PWM with the same period and different duties and complementary PWM with the dead time set can be output.
- Real Time Clock (RTC)
 - 1 channels (99 years calendar, alarm, revision of the clock)
- Watchdog timer (WDT)
 - Non-maskable interrupt and reset
 - Free running
 - Overflow period: 4 types selectable (125ms, 500ms, 2s, and 8s when LSCLK = 32.768 kHz)
- Synchronous serial port (SSIOF/SSIO)
 - without FIFOs (SSIO) : 1 channel
 - with 16-byte transmits and receives FIFOs (SSIOF) : 1 channel
 - Master/slave selectable
 - LSB first/MSB first selectable
 - Clock polarity (data out at rising edge and data in at falling edge/data out at falling edge and data in at rising edge) selectable
 - 8-bit length/16-bit length selectable
 - Initial clock level (High start/Low start) selectable
 - supports slave-select signal (only SSIOF)
- UART (UARTF/UART)
 - without FIFOs (UART) : 1channel
 - with 16-byte transmits and receives FIFOs (UARTF) :1 channels
 - Full duplex buffer system
 - Communication speed: Settable within the range of 2400bps to 115200bps.
 - Programmable interface (data length, parity, stop bits selectable)

- I²C bus interface (I²CF/I²C)
 - without FIFOs(I²C) :1 channel
 - with 16-byte transmits and receives FIFOs (I²CF) : 1 channels
 - Master/slave function (only I2CF)
 - Fast mode (400 kHz), standard mode (100 kHz)
- USB full-speed device
 - Compliant with Universal Serial Bus (USB)
 - Full speed (12 Mbps) 1 port.
 - End points: 5 or 6
 - Supports all data transfer types (control transfer, bulk transfer, interrupt transfer, isochronous transfer).
 - Built-in SOF generation and CRC5/16 generation functions
 - Access size to data transfer FIFOs: 8 bits/16 bits/32 bits
- General-purpose ports (PORT)
 - Input/output port × 38 channels (including secondary or tertiary or quaternary or quinary functions).
(ML630Q464 and ML630Q466: including LCD com/seg ports (each 20 ports))
- RC oscillation type A/D converter (RC-ADC)
 - Time division × 2 channels
 - Starting by trigger of Timer/FTM function.
 - 24-bit counter
- Successive approximation type A/D converter (SA-ADC)
 - Input × 12 channels
 - 12-bit A/D converter
 - Starting by trigger of Timer/FTM function.
 - Capacitive touch sense function
- Analog Comparator (CMP)
 - Input × 2ch
 - Common mode input voltage: 0.2V to V_{DD} − 0.2V
 - Input offset voltage: 30mV(max)
 - Interrupt allow edge selection and sampling selection
- Voltage Level Supervisor (VLS)
 - Threshold voltages: One of 64 levels
 - Accuracy: ±3%
 - Interrupt or Reset generation are selectable
 - Voltage measurement with voltage input pin or V_{DD} pin
- Low Level Detector(LLD)
 - Judgment Voltage: 1.8V±0.2V
 - Can be used as low level detection reset.
- LCD driver
 - Maximum 400 dots (50 segment x 8 common)
 - 1/1 to 1/8 duty
 - 1/2, 1/3 bias (built-in bias generation circuit)
 - Frame frequency selectable
 - Bias voltage multiplying clock selectable (5 types)
 - Contrast adjustment (32 steps)
 - 4 operating mode: LCD drive stop, LCD display, all LCDs on, all LCDs off
 - Programmable display allocation function
- Random number generator (RANDOM)
 - Generates 8-bit random numbers

- AES
 - 128-bit Common key
 - Supports key sizes of 128, 192, and 256 bits
 - Supports ECB, CBC, and CTR modes
- Reset
 - Reset by the RESET_N pin input
 - Reset by power-on detection
 - Reset by overflow of watchdog timer (WDT)
 - Reset by threshold detection in Voltage Level Supervisor(VLS)
 - Reset by low level detection in Low Level Detector(LLD)
 - Reset by the low-speed crystal oscillation stop detection
 - Reset by SYSRESETREQ of ARM®Cortex®-M0+ (software reset)
- Clock
 - Low-speed clock:
 - Crystal oscillation (32.768 kHz)
 - Built-in RC oscillation (32.768kHz)
 - High-speed clock:
 - PLL (24 MHz) generated from Crystal oscillation (32.768 kHz)
 - Built-in RC oscillation (16MHz)
- Power management
 - HALT mode: Instruction execution by CPU is suspended. All peripheral circuits can keep in operating states.
 - HALT-H mode: Instruction execution by CPU is suspended. Stop of high-speed oscillation automatically. All peripheral circuits can keep in operating states.
 - DEEP-HALT mode: Instruction execution by CPU is suspended. Some peripheral circuits(Timer, LTBC etc.) can keep in operating states.
 - ULTRA-DEEP-HALT mode: Instruction execution by CPU is suspended. Some peripheral circuits(Timer, LTBC etc.) can keep in operating states, at $V_{DD} > 2.5V$.
 - STOP mode: Stop of low-speed oscillation and high-speed oscillation (Operations of CPU and peripheral circuits are stopped.)
 - Clock gear: The frequency of high-speed system clock can be changed by software (1/1, 1/2, 1/4, 1/8,1/16,1/32 of the oscillation clock)
 - Block Control Function: Power down (reset registers and stop clock supply) the circuits of unused peripherals.
- Guaranteed operating range
 - Operating temperature (ambient) : $-40^{\circ}C$ to $+85^{\circ}C$
 - Operating voltage: $V_{DD} = 1.8V$ to $3.6V$
- Supply current (Typ)
 - High-speed operation (24 MHz) : 250uA/MHz
 - ULTRA-DEEP-HALT : 0.80uA
- Package and shipping form
 - 100-pin plastic TQFP
 - Tray
 - ML630Q464-xxxTBZWAX
 - ML630Q466-xxxTBZWAX

■ PIN CONFIGURATION

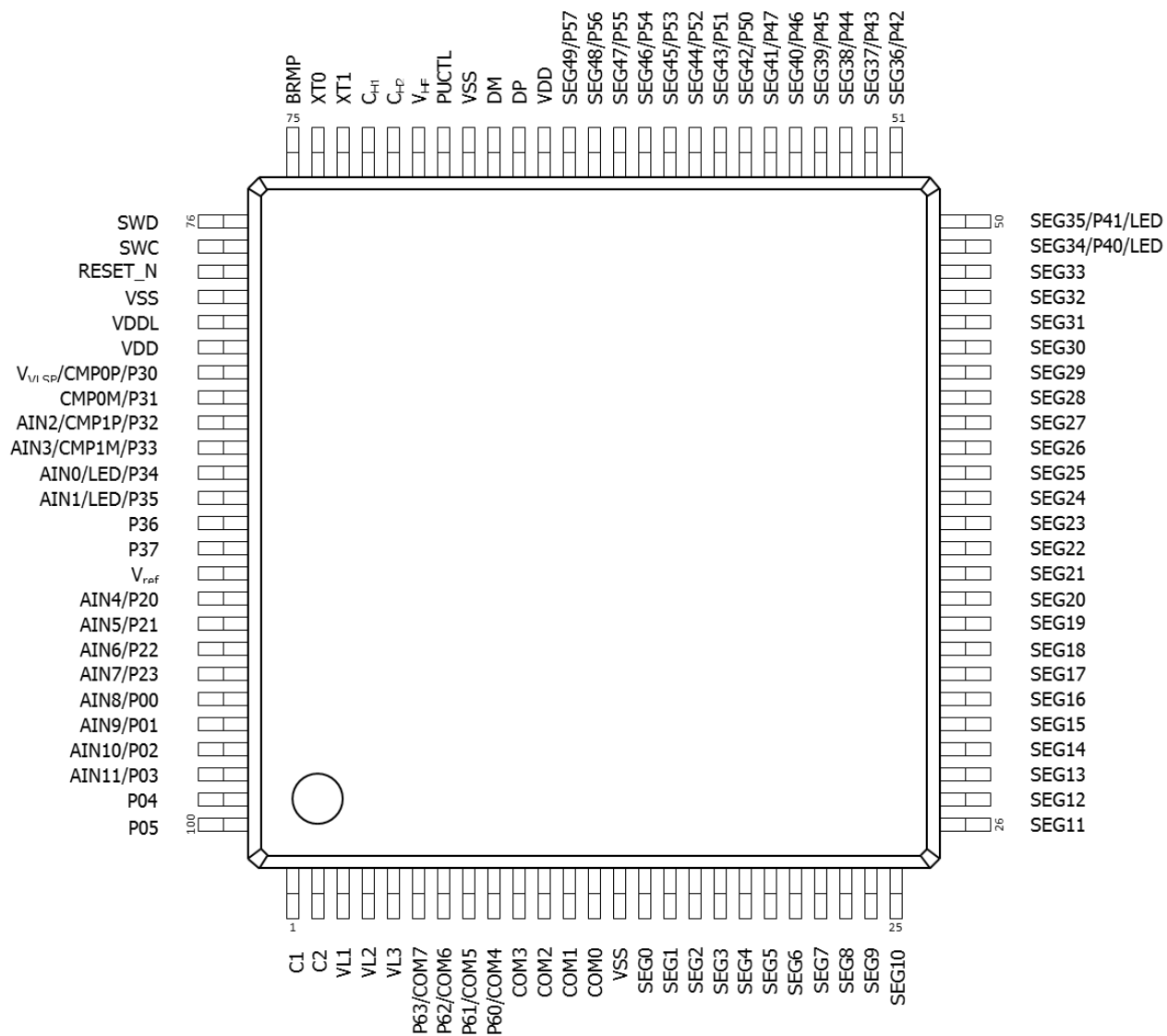


Figure 2. Pin Layout of ML630Q464/Q466

■ PIN LIST

PIN No.	.Reset State	Primary Function		Secondary Function		Tertiary Function		Quaternary Function		Quinary Function	
		Pin name	I/O	Pin name	I/O	pin name	I/O	pin name	I/O	pin name	I/O
14 68 79	–	V _{SS}	–	–	–	–	–	–	–	–	–
65 81	–	V _{DD}	–	–	–	–	–	–	–	–	–
80	–	V _{DDL}	–	–	–	–	–	–	–	–	–
70	–	V _{HF}	–	–	–	–	–	–	–	–	–
90	–	V _{REF}	–	–	–	–	–	–	–	–	–
74	–	XT0	–	–	–	–	–	–	–	–	–
73	–	XT1	–	–	–	–	–	–	–	–	–
78	Pull-up Input	RESET_N	I	–	–	–	–	–	–	–	–
77	Pull-up Input	SWC	I	–	–	–	–	–	–	–	–
76	Pull-up Input	SWD	I/O	–	–	–	–	–	–	–	–
75	Pull-down Input	BRMP	I	–	–	–	–	–	–	–	–
95	Hi-Z output	P00/ EX100/ AIN8	I/O	IN0	I	SOUT0	O	RXDF0	I	–	–
96	Hi-Z output	P01/ EX101/ AIN9	I/O	CS0	O	SIN0	I	TXDF0	O	–	–
97	Hi-Z output	P02/ EX102/ AIN10	I/O	RCT0	O	SCK0	I/O	TMOUT0	O	–	–
98	Hi-Z output	P03/ EX103/ AIN11	I/O	RS0	O	–	–	TMOUT1	O	–	–
99	Hi-Z output	P04/ EX104	I/O	RT0	O	–	–	–	–	–	–
100	Hi-Z output	P05/ EX105	I/O	RCM	O	–	–	–	–	–	–
91	Hi-Z output	P20/ EX120/ AIN4	I/O	IN1	I	SOUTF0	O	–	–	–	–
92	Hi-Z output	P21/ EX121/ AIN5	I/O	CS1	O	SINF0	I	–	–	–	–
93	Hi-Z output	P22/ EX122/ AIN6	I/O	RS1	O	SCKF0	I/O	TMOUT2	O	–	–
94	Hi-Z output	P23/ EX123/ AIN7	I/O	RT1	O	SSF0	I/O	TMOUT3	O	–	–
82	Hi-Z output	P30/ EX130/ CMP0P VLSin	I/O	SDAF0	I/O	SOUT0	O	–	–	–	–
83	Hi-Z output	P31/ EX131/ CMP0M	I/O	SCLF0	I/O	SIN0	I	–	–	–	–
84	Hi-Z output	P32/ EX132/ CMP1P/ AIN2	I/O	RXDF0	I	SCK0	I/O	TMOUT4	O	–	–
85	Hi-Z output	P33/ EX133/ CMP1M/ AIN3	I/O	TXDF0	O	32kCLKO	O	TMOUT5	O	–	–
86	Hi-Z output	P34/ EX134/ AIN0 LED	I/O	SDA1	I/O	SOUTF0	O	–	–	–	–
87	Hi-Z output	P35/ EX135/ AIN1 LED	I/O	SCL1	O	SINF0	I	–	–	–	–
88	Hi-Z output	P36/ EX136/ TMCK14	I/O	RXD0	I	SCKF0	I/O	TMOUT6	O	–	–
89	Hi-Z output	P37/ EX137/ TMCK15	I/O	TXD0	O	SSF0	I/O	TMOUT7	O	–	–
13 to 10	Low Level Output	COM0 to COM3	O	–	–	–	–	–	–	–	–
9	Hi-Z output	P60/ EX160	I/O	COM4	O	–	–	–	–	–	–
8	Hi-Z output	P61/ EX161	I/O	COM5	O	–	–	–	–	–	–
7	Hi-Z output	P62/ EX162	I/O	COM6	O	–	–	–	–	–	–
6	Hi-Z output	P63/ EX163	I/O	COM7	O	–	–	–	–	–	–
15 to 48	Low Level Output	SEG0 to SEG33	O	–	–	–	–	–	–	–	–
49	Hi-Z output	P40/ EX140/ LED	I/O	SDAF0	I/O	SOUT0	O	–	–	SEG34	O

PIN No.	.Reset State	Primary Function		Secondary Function		Tertiary Function		Quaternary Function		Quinary Function	
		Pin name	I/O	Pin name	I/O	pin name	I/O	pin name	I/O	pin name	I/O
50	Hi-Z output	P41/ EXI41/ LED	I/O	SCLF0	I/O	SIN0	I	-	-	SEG35	O
51	Hi-Z output	P42/ EXI42/ TMCKI0	I/O	RXDF0	I	SCK0	I/O	TMOUT8	O	SEG36	O
52	Hi-Z output	P43/ EXI43/ TMCK1	I/O	TXDF0	O	32kCLKO	O	TMOUT9	O	SEG37	O
53	Hi-Z output	P44/ EXI44	I/O	SDA1	I/O	SOUTF0	O	-	-	SEG38	O
54	Hi-Z output	P45/ EXI45	I/O	SCL1	O	SINF0	I	-	-	SEG39	O
55	Hi-Z output	P46/ EXI46/ TMCK2	I/O	RXD0	I	SCKF0	I/O	TMOUTA	O	SEG40	O
56	Hi-Z output	P47/ EXI47/ TMCK3	I/O	TXD0	O	SSF0	I/O	TMOUTB	O	SEG41	O
57	Hi-Z output	P50/ EXI50	I/O	SDAF0	I/O	SOUT0	O	-	-	SEG42	O
58	Hi-Z output	P51/ EXI51	I/O	SCLF0	I/O	SIN0	I	-	-	SEG43	O
59	Hi-Z output	P52/ EXI52	I/O	RXDF0	I	SCK0	I/O	TMOUTC	O	SEG44	O
60	Hi-Z output	P53/ EXI53	I/O	TXDF0	O	32kCLKO	O	TMOUTD	O	SEG45	O
61	Hi-Z output	P54/ EXI54	I/O	SDA1	I/O	SOUTF0	O	-	-	SEG46	O
62	Hi-Z output	P55/ EXI55	I/O	SCL1	O	SINF0	I	-	-	SEG47	O
63	Hi-Z output	P56/ EXI56/ TMCKI6	I/O	RXD0	I	SCKF0	I/O	TMOUTE	O	SEG48	O
64	Hi-Z output	P57/ EXI57/ TMCKI7	I/O	TXD0	O	SSF0	I/O	TMOUTF	O	SEG49	O
66	Hi-Z output	DP	I/O	-	-	-	-	-	-	-	-
67	Hi-Z output	DM	I/O	-	-	-	-	-	-	-	-
69	Low output	PUCTL	O	-	-	-	-	-	-	-	-
3	-	V _{L1}	-	-	-	-	-	-	-	-	-
4	-	V _{L2}	-	-	-	-	-	-	-	-	-
5	-	V _{L3}	-	-	-	-	-	-	-	-	-
1	-	C ₁	-	-	-	-	-	-	-	-	-
2	-	C ₂	-	-	-	-	-	-	-	-	-
71	-	C _{H1}	-	-	-	-	-	-	-	-	-
72	-	C _{H2}	-	-	-	-	-	-	-	-	-

■ PIN DESCRIPTION

In the table below indicates the functional pin description.

The pin name represents the function pin name of the primary function of each terminal, The pin mode represents the set of mode register of Port Control.

(1st:primary function, 2nd:secondary function, 3rd: tertiary function, 4th: quaternary function, 5th:quinary function)

Pin name	I/O	Description	LSI pin name	Pin mode	Logic
System					
RESET_N	I	Reset input pin. When this pin is set to a "L" level, system reset mode is set and the internal section is initialized. When this pin is set to a "H" level subsequently, program execution starts. A pull-up resistor is internally connected.	RESET_N	-	L
BRMP	I	Remapping control input (for firmware update) Based on the BRMP pin setting at the time of the reset release, Bank0 is remapped.	BRMP	-	H
XT0	I	Crystal connection pin for low-speed clock.	XT0	-	-
XT1	O	Capacitors C _{DL} and C _{GL} are connected across this pin and V _{SS} as required.	XT1	-	-
32kCLKO	O	Low-speed clock output pin	P33,P43,P53	2 nd	
General-purpose input/output port					
P00-P05	I/O	General-purpose input/output port.	P00-P05	1 st	-
P20-P23	I/O	General-purpose input/output port.	P20-P23	1 st	-
P30-P37	I/O	General-purpose input/output port.	P30-P37	1 st	-
P40-P47	I/O	General-purpose input/output port.	P40-P47	1 st	-
P50-P57	I/O	General-purpose input/output port.	P50-P57	1 st	-
P60-P63	I/O	General-purpose input/output port.	P60-P63	1 st	-
External interrupt					
EXI00-05 EXI20-23 EXI30-37 EXI40-47 EXI50-57 EXI60-63	I	External maskable interrupt input pins. It is possible, for each bit, to specify whether the interrupt is enabled and select the interrupt edge by software.	P00-P05 P20-P23 P30-P37 P40-P47 P50-P57 P60-P63	1 st	H/L
LED					
LED	O	N-channel open drain output pins to drive LED.	P34,P35,P40,P41	1 st	-
UART					
TXD0	O	UART data output pin.	P37,P47,P57	2 nd	-
RXD0	I	UART data input pin.	P36,P46,P56	2 nd	-
TXDF0	O	UARTF with FIFO data output pin.	P01,P33,P43,P53	2 nd	-
RXDF0	I	UARTF with FIFO data input pin.	P00,P32,P42,P52	2 nd	-
I²C bus interface					
SDA1	I/O	I2C1 data input/output pin. This pin has an NMOS open drain output. When using this pin as a function of the I ² C, externally connect a pull-up resistor.	P34,P44,P54	2 nd	-
SCL1	O	I2C1 clock output pin. This pin has an NMOS open drain output. When using this pin as a function of the I ² C, externally connect a pull-up resistor.	P35,P45,P55	2 nd	-
SDAF0	I/O	I2CF0 data input/output pin. This pin has an NMOS open drain output. When using this pin as a function of the I ² C, externally connect a pull-up resistor.	P30,P40,P50	2 nd	-
SCLF0	I/O	I2CF0 clock input/output pin. This pin has an NMOS open drain output. When using this pin as a function of the I ² C, externally connect a pull-up resistor.	P31,P41,P51	2 nd	-

Pin name	I/O	Description	LSI pin name	Pin mode	Logic
Synchronous serial					
SCK0	I/O	Synchronous serial (SSIO) clock input/output pin.	P02,P32,P42,P52	3 rd	-
SIN0	I	Synchronous serial (SSIO) data input pin.	P01,P31,P41,P51	3 rd	-
SOUT0	O	Synchronous serial (SSIO) data output pin.	P00,P30,P40,P50	3 rd	-
SCKF0	I/O	Synchronous serial with FIFO (SSIOF) clock input/output pin.	P22,P36,P46,P56	3 rd	-
SINF0	I	Synchronous serial with FIFO (SSIOF) data input pin.	P21,P35,P45,P55	3 rd	-
SOUTF0	O	Synchronous serial with FIFO (SSIOF) data output pin.	P20,P34,P44,P54	3 rd	-
SSF0	I/O	Synchronous serial with FIFO (SSIOF) select input/output pin.	P23,P37,P47,P57	3 rd	L
FTM					
TMOUT0-9 TMOUTA-F	O	FTM output pin.	P02,P03,P22,P23 P32,P33,P36,P37 P42,P43,P46,P47 P52,P53,P56,P57	4 th	-
TMCKI0-7	I	External clock input pin for FTM.	P42,P43,P46,P47 P36,P37,P56,P57	1 st	-
RC oscillation type A/D converter					
IN0	I	Oscillation input pin of Channel 0.	P00	2 nd	-
CS0	O	Reference capacitor connection pin of Channel 0.	P01	2 nd	-
RS0	O	Reference resistor connection pin of Channel 0.	P03	2 nd	-
RT0	O	Resistor sensor connection pin for measurement of Channel 0.	P04	2 nd	-
RCT0	O	Resistor/capacitor sensor connection pin of Channel 0 for measurement.	P02	2 nd	-
RCM	O	RC oscillation monitor pin.	P05	2 nd	-
IN1	I	Oscillation input pin of Channel 1.	P20	2 nd	-
CS1	O	Reference capacitor connection pin of Channel 1.	P21	2 nd	-
RS1	O	Reference resistor connection pin of Channel 1.	P22	2 nd	-
RT1	O	Resistor sensor connection pin for measurement of Channel 1.	P23	2 nd	-
Successive approximation type A/D converter					
V _{REF}	I	Reference power supply pin for successive approximation type A/D converter.	V _{REF}	-	-
AIN0-11	I	Analog input for successive approximation type A/D converter.	(AIN0-3) P32-35, (AIN4-7) P20-23, (AIN8-11) P00-03	1 st	-
Analog comparator					
CMP0P	I	Comparator0 Non-inverted input pin.	P30	1 st	-
CMP0M	I	Comparator0 Inverted input pin.	P31	1 st	-
CMP1P	I	Comparator1 Non-inverted input pin.	P32	1 st	-
CMP1M	I	Comparator1 Inverted input pin.	P33	1 st	-
USB FS Device					
DP	I/O	USB dev D+ pin.	DP	-	-
DM	I/O	USB dev D- pin.	DM	-	-
PUCTL	O	USB dev pull-up control	PUCTL	-	-
DEBUG Interface					
SWC	I	Serial clock of Serial Wire Debug Port	SWC	-	-
SWD	I/O	Serial I/O data of Serial Wire Debug Port	SWD	-	-

Pin name	I/O	Description	LSI pin name	Pin mode	Logic
Power supply					
V _{SS}	-	Negative power supply pin.	V _{SS}	-	-
V _{DD}	-	Positive power supply pin.	V _{DD}	-	-
V _{DDL}	-	Positive power supply pin (internally generated) for internal logic. Capacitors C _L is connected between this pin and V _{SS} .	V _{DDL}	-	-
V _{HF}	-	Positive power supply pin (internally generated) for built-in halver circuit. Capacitor C _{VH} is connected between this pin and V _{SS} .	V _{HF}	-	-
C _{H1} – C _{H2}	-	Capacitor pins of built-in halver circuit	C _{H1} – C _{H2}	-	-
LCD driver					
COM0 – COM3	-	Common pins of LCD driver	COM0 – COM3	-	-
COM4 – COM7	-	Common pins of LCD driver	P60-P63	2 nd	-
SEG0 – SEG33	-	Segment pins of LCD driver	SEG0 – SEG33	-	-
SEG34 – SEG49	-	Segment pins of LCD driver	P40-P47 P50-P57	5 th	-
C ₁ – C ₂	-	Capacitor pins of built-in generation bias circuit	C ₁ – C ₂	-	-
V _{L1} – V _{L3}	-	Reference voltage input pins of built-in bias generation circuit	V _{L1} – V _{L3}	-	-

■ TERMINATION OF UNUSED PINS

Table 1 shows methods of terminating the unused pins.

Table 1 Termination of Unused Pins

Pin	Recommended pin termination
RESET_N	Connect to V _{DD}
BRMP	Connect to V _{SS}
SWC	Connect a pull-up resistor.
SWD	Connect a pull-up resistor.
V _{REF}	Connect to V _{DD}
P00 to P05	open
P20 to P23	open
P30 to P37	open
P40 to P47	open
P50 to P57	open
P60 to P63	open
COM0 to COM3	open
SEG0 to SEG33	open
DP, DM, PUCTL	open
V _{L1} , V _{L2} , V _{L3}	open
C ₁ , C ₂	open

[Note]

For unused input ports or unused input/output ports, if the corresponding pins are configured as high-impedance inputs and left open, the supply current may become excessively large. Therefore, it is recommended to configure those pins as either inputs with a pull-down resistor/pull-up resistor or outputs.

■ Electrical Characteristics

● ABSOLUTE MAXIMUM RATINGS

(V_{SS}=0V)

Parameter	Symbol	Condition	Rating	Unit
Power supply voltage 1	V _{DD}	Ta=25°C	-0.3 to +4.6	V
Power supply voltage 2	V _{DDL}	Ta=25°C	-0.3 to +2.0	V
Power supply voltage 3	V _{L1-3}	Ta=25°C	-0.3 to +6.0	V
Input voltage(P00-P05, P20-P23, P30-P35, SWC, SWD, BRMP, RESET_N, DP, DM)	V _{IN}	Ta=25°C	-0.3 to V _{DD} +0.3	V
Input voltage (5 V tolerant) (P36, P37, P40-P47, P50-P57, P60-P63)	V _{INT}	Ta=25°C	-0.3 to +6.0	V
Output voltage 1	V _{OUT1}	Ta=25°C	-0.3 to V _{DD} +0.3	V
Output voltage 2 (COM0 to COM7 SEG0 to SEG49)	V _{OUT2}	Ta=25°C	-0.3 to V _{L1-3} +0.3	V
Output current 1	I _{OUT1}	Ta=25°C	-12 to +11	mA
Output current 2	I _{OUT2}	Ta=25°C	-12 to +20	mA
Power dissipation	PD	Ta=25°C	0.9	W
Storage temperature	T _{STG}	–	-55 to +150	°C

●RECOMMENDED OPERATING CONDITIONS

(V_{SS}=0V)

Parameter	Symbol	Condition	Range	Unit
Operating temperature (Ambience)	T _{OP}	–	-40 to +85	°C
Operating voltage	V _{DD}	–	1.8 to 3.6	V
Reference voltage	V _{REF}	–	1.8 to V _{DD}	V
Operating frequency (CPU)	f _{OP}	–	LSCLK:32.768k HSCLK:500k to 24M	Hz
Low speed crystal oscillation frequency	f _{XTL}	–	32.768k	Hz
Low speed crystal oscillation external capacitor 1	C _{DL}	Using VT-200-FL(from SII)	6.8 to 12	pF
	C _{GL}		6.8 to 12	
Low speed crystal oscillation external capacitor 2	C _{DL}	Using DT-26(from Daishinku)	12 to 16	pF
	C _{GL}		12 to 16	
Low speed crystal *1 oscillation external capacitor 3	C _{DL}	Using VT-200-F(from SII)	12 to 22	pF
	C _{GL}		12 to 22	
V _{DDL} external capacitor *2	C _L	ESR ≤500mΩ	2.2 ± 30%	μF
V _{L1,2,3pin} external capacitor	C _{a,b,c}	–	1.0 ± 30%	μF
C ₁ -C ₂ external capacitor	C ₁₂	–	1.0 ± 30%	μF
C _{H1} , C _{H2} external capacitor	C _{H12}	–	1.0 ± 30%	μF
V _{HF} external capacitor	C _{HF}	–	1.0 ± 30%	μF

*1 : Please use this crystal except DEEPHALT mode because this LSI may not be functioning at DEEPHALT mode with the crystal.
Please evaluate the matching when other crystal oscillator/ceramic oscillator is used.

*2 : Please evaluate on user's conditions, put on C_{L0}(= 0.1μF) if necessary.

See the application note; "Precautions for MCU board design" for details, when designing MCU board.

●Operating Conditions of Flash Memory

(V_{SS}= 0V)

Parameter	Symbol	Condition	Range	Unit	
Operating temperature (Ambience)	T _{OP}	Data area : write/erase	-40 to +85	°C	
		Program area : write/erase	0 to +40	°C	
Operating voltage Write time	V _{DD}	Write/erase	1.8 to 3.6	V	
	C _{EPD}	Data area (1,024B x 2)	10,000	times	
	C _{EPP}	Program area	100	times	
Erase unit	-	Block erase	Program area	8	KB
			Data area	2	
		Sector erase	1	KB	
Erase time(Maximum)	-	Block erase/Sector erase	100	ms	
Write unit	-	-	1 word (4 byte)	-	

●AC characteristics (Oscillation)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
Low speed crystal oscillation start time	T _{XTL}	–	–	–	2	s	1
Low speed built-in RC oscillation frequency ^{*1*2*3}	f _{LCR}	Ta=25°C	Typ -1.5%	32.768	Typ +1.5%	kHz	
		Ta=-40 to 85°C	typ-5%	32.768	typ+5%		
High speed build-in RC oscillation frequency ^{*1*2}	f _{HCR}	Ta=25°C	typ -1%	16	typ +1%	MHz	
		Ta=-40 to 85°C	typ -5%	16	typ +5%		
PLL frequency	f _{PLL}	f _{XTL} =32.768kHz	typ -0.25%	24	typ +0.25%	MHz	
Low speed crystal oscillation stop detection time	T _{STOP}	–	–	600	–	μs	

*1 : Mean value of 1024 cycle.

*2 : Guarantee value at the time of the shipment.

*3 : Except DeepHALT mode and Ultra-DeepHALT mode.

●DC Characteristics (IDD)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating ^{*1}			Unit	Measuring circuit
			Min.	Typ.	Max.		
Power consumption 1	IDD1	CPU is Stopped Low/High-speed oscillation is stopped	Ta=25°C	–	0.70	2.5	μA
			Ta=-40 to 85°C	–	–	28	
Power consumption 2	IDD2-1	ULTRA-DEEP-HALT mode ^{*3*4} (LBTC function) Low-speed crystal oscillating (32.768kHz) High-speed oscillation is stopped. 2.5V ≤ V _{DD}	Ta=25°C	–	0.80	2.5	μA
			Ta=-40 to 85°C	–	–	20	
	IDD2-2	DEEP-HALT mode ^{*3*4} (LBTC function) Low-speed crystal oscillating (32.768kHz) High-speed oscillation is stopped.	Ta=25°C	–	1.30	3.0	μA
			Ta=-40 to 85°C	–	–	28	
Power consumption 3	IDD3	HALT mode ^{*3*4} (LTBC function) Low-speed crystal oscillating (32.768kHz) High speed oscillation is stopped.	Ta=25°C	–	2.2	5.0	μA
			Ta=-40 to 85°C	–	–	32	
Power consumption 4	IDD4	CPU Low-speed ^{*2*4} Low-speed crystal oscillating High speed oscillation is stopped.	Ta=25°C	–	9.0	14	μA
			Ta=-40 to 85°C	–	–	45	
Power consumption 5	IDD5	CPU High-speed(16MHz) ^{*2*4} High-speed Built-in RC oscillating	Ta=25°C	–	3.8	5.0	mA
			Ta=-40 to 85°C	–	–	5.5	
Power consumption 6	IDD6	CPU High-speed(24MHz) ^{*2*4} High-speed PLL oscillating	Ta=25°C	–	6.0	7.0	mA
			Ta=-40 to 85°C	–	–	7.5	

*1 : typ.rating is V_{DD}=3.0V

*2 : at CPU activity rate =100% (No HALT state)

*3 : using 32.768KHz crystal oscillator VT-200-FL (from SII)(C_{GL}/C_{DL} = 12pF)
using 32.768KHz crystal oscillator DT-26(from Daishinku)(C_{GL}/C_{DL} = 12pF)

*4 : CLKCON valid bits are "0", RSTCON valid bits are "1"

1

●DC Characteristics (VLS)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
VLS judge voltage (V _{DD} =fall)	V _{VLS}	VLSLV[5:0] = 00H ^{*1}	Typ. -3%	1.200	Typ. +3%	V	1
		VLSLV[5:0] = 01H ^{*1}		1.225			
		VLSLV[5:0] = 02H ^{*1}		1.250			
		VLSLV[5:0] = 03H ^{*1}		1.275			
		VLSLV[5:0] = 04H ^{*1}		1.300			
		VLSLV[5:0] = 05H ^{*1}		1.325			
		VLSLV[5:0] = 06H ^{*1}		1.350			
		VLSLV[5:0] = 07H ^{*1}		1.375			
		VLSLV[5:0] = 08H ^{*1}		1.400			
		VLSLV[5:0] = 09H ^{*1}		1.425			
		VLSLV[5:0] = 0AH ^{*1}		1.450			
		VLSLV[5:0] = 0BH ^{*1}		1.475			
		VLSLV[5:0] = 0CH ^{*1}		1.500			
		VLSLV[5:0] = 0DH ^{*1}		1.525			
		VLSLV[5:0] = 0EH ^{*1}		1.550			
		VLSLV[5:0] = 0FH ^{*1}		1.575			
		VLSLV[5:0] = 10H ^{*1}		1.600			
		VLSLV[5:0] = 11H ^{*1}		1.625			
		VLSLV[5:0] = 12H ^{*1}		1.650			
		VLSLV[5:0] = 13H ^{*1}		1.675			
		VLSLV[5:0] = 14H ^{*1}		1.700			
		VLSLV[5:0] = 15H ^{*1}		1.725			
		VLSLV[5:0] = 16H ^{*1}		1.750			
		VLSLV[5:0] = 17H ^{*1}		1.775			
		VLSLV[5:0] = 18H		1.800			
		VLSLV[5:0] = 19H		1.825			
		VLSLV[5:0] = 1AH		1.850			
		VLSLV[5:0] = 1BH		1.875			
		VLSLV[5:0] = 1CH		1.900			
		VLSLV[5:0] = 1DH		1.925			
		VLSLV[5:0] = 1EH		1.950			
		VLSLV[5:0] = 1FH		1.975			
		VLSLV[5:0] = 20H		2.000			
VLSLV[5:0] = 21H	2.050						
VLSLV[5:0] = 22H	2.100						
VLSLV[5:0] = 23H	2.150						
VLSLV[5:0] = 24H	2.200						
VLSLV[5:0] = 25H	2.250						
VLSLV[5:0] = 26H	2.300						
VLSLV[5:0] = 27H	2.350						
VLSLV[5:0] = 28H	2.400						
VLSLV[5:0] = 29H	2.450						
VLSLV[5:0] = 2AH	2.500						
VLSLV[5:0] = 2BH	2.550						
VLSLV[5:0] = 2CH	2.600						

		VLSLV[5:0] = 2DH		2.650			
		VLSLV[5:0] = 2EH		2.700			
		VLSLV[5:0] = 2FH		2.750			
		VLSLV[5:0] = 30H		2.800			
		VLSLV[5:0] = 31H		2.850			
		VLSLV[5:0] = 32H		2.900			
		VLSLV[5:0] = 33H		2.950			
		VLSLV[5:0] = 34H		3.000			
		VLSLV[5:0] = 35H		3.050			
		VLSLV[5:0] = 36H	Typ. -3%	3.100	Typ. +3%	V	
		VLSLV[5:0] = 37H		3.150			
		VLSLV[5:0] = 38H		3.200			
		VLSLV[5:0] = 39H		3.250			
		VLSLV[5:0] = 3AH		3.300			
		VLSLV[5:0] = 3BH		3.350			
		VLSLV[5:0] = 3CH		3.400			
		VLSLV[5:0] = 3DH		3.450			
		VLSLV[5:0] = 3EH		3.500			
		VLSLV[5:0] = 3FH		3.550			1
V _{VLS} Hysteresis width (V _{DD} =rise)	H _{VLS}	–	V _{VLS} x 1.0%	V _{VLS} x 2.7%	V _{VLS} x 4.5%	V	

VLSLV[3:0] are bits of the VLSCON register to change detection voltage level.

*1: Setable only at the time of select to V_{VLSP} pin.

●DC characteristics (LLD)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
LLD judge Voltage	VLLR	–	1.60	1.80	2.00	V	1

●DC/AC characteristics (Analog comparator)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
Common Input voltage range	V _{CMPI}	–	0.2	–	V _{DD} -0.2	V	1
Input offset voltage	V _{CMPOF}	–	-30	–	30	mV	
Comparator judge time	T _{CMP}	CMPP- CPM =40mV	–	–	2	μs	

●DC characteristics (LCD Driver)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, T_a=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit	
			Min.	Typ.	Max.			
V _{L1} voltage	V _{L1}	V _{DD} = 3.0V, T _j = 25°C	LCN[4:0] = 00H* ₂	0.89	0.94	0.99	V	1
			LCN[4:0] = 01H* ₂	0.91	0.96	1.01		
			LCN[4:0] = 02H* ₂	0.93	0.98	1.03		
			LCN[4:0] = 03H* ₂	0.95	1.00	1.05		
			LCN[4:0] = 04H* ₂	0.97	1.02	1.07		
			LCN[4:0] = 05H* ₂	0.99	1.04	1.09		
			LCN[4:0] = 06H* ₂	1.01	1.06	1.11		
			LCN[4:0] = 07H* ₂	1.03	1.08	1.13		
			LCN[4:0] = 08H* ₂	1.05	1.10	1.15		
			LCN[4:0] = 09H* ₂	1.07	1.12	1.17		
			LCN[4:0] = 0AH* ₂	1.09	1.14	1.19		
			LCN[4:0] = 0BH* ₂	1.11	1.16	1.21		
			LCN[4:0] = 0CH* ₂	1.13	1.18	1.23		
			LCN[4:0] = 0DH* ₂	1.15	1.20	1.25		
			LCN[4:0] = 0EH* ₂	1.17	1.22	1.27		
			LCN[4:0] = 0FH* ₂	1.19	1.24	1.29		
			LCN[4:0] = 10H	1.21	1.26	1.31		
			LCN[4:0] = 11H	1.23	1.28	1.33		
			LCN[4:0] = 12H	1.25	1.30	1.35		
			LCN[4:0] = 13H	1.27	1.32	1.37		
			LCN[4:0] = 14H	1.29	1.34	1.39		
			LCN[4:0] = 15H	1.31	1.36	1.41		
			LCN[4:0] = 16H	1.33	1.38	1.43		
			LCN[4:0] = 17H	1.35	1.40	1.45		
LCN[4:0] = 18H	1.37	1.42	1.47					
LCN[4:0] = 19H	1.39	1.44	1.49					
LCN[4:0] = 1AH	1.41	1.46	1.51					
LCN[4:0] = 1BH	1.43	1.48	1.53					
LCN[4:0] = 1CH	1.45	1.50	1.55					
LCN[4:0] = 1DH	1.47	1.52	1.57					
LCN[4:0] = 1EH	1.49	1.54	1.59					
LCN[4:0] = 1FH	1.51	1.56	1.61					
V _{L1} temperature deviation* ¹	ΔV _{L1}	V _{DD} = 3.0V	–	–0.06	–	%/°C		
V _{L1} voltage dependency* ¹	ΔV _{L1}	V _{DD} = 1.8 to 3.6V	–	5	20	mV/V		
V _{L2} voltage	V _{L2}	V _{DD} = 3.0V, T _j = 25°C 1MΩ load (V _{L3} –V _{SS})	Typ. –10%	V _{L1} ×2	Typ. +4%	V		
V _{L3} voltage	V _{L3}		Typ. –10%	V _{L1} ×3	Typ. +4%			
LCD bias voltage generation time	T _{BIAS}	–	–	–	600	ms		

*¹: V_{L1} can not exceed V_{DD} level. The maximum V_{L1} becomes V_{DD} level when the V_{L1} calculated by the temperature deviation and voltage dependency is going to exceed the V_{DD} level.

*²: 1/3 bias only.

●DC characteristics (VOHL, IOHL)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, T_a=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
Output voltage 1 (P00-P05, P20-P23, P30-P37, P40-P47, P50-P57,, P60-P63, SWD,PUCTL)	VOH1	IOH=-1.0mA	V _{DD} -0.5	-	-	V	2
	VOL1	IOL=+0.5mA	-	-	0.4		
Output voltage 2 (P34, P35, P40, P41) (LED mode is selected)	VOL2	2.7V ≤ V _{DD} ≤ 3.6V IOL=+5.0mA	-	-	0.6		
		IOL=+2.0mA	-	-	0.4		
Output voltage 3 (P30, P31, P34, P35, P40, P41, P44, P45, P50, P51, P54, P55) (I ² C mode is selected)	VOL3	IOL3= +3mA (I ² Cspec) (V _{DD} ≥ 2V)	-	-	0.4		
Output voltage 4 (P30, P31, P34, P35, P40, P41, P44, P45, P50, P51, P54, P55) (I ² C mode is selected)	VOL4	IOL4= +2mA(I ² Cspec) (V _{DD} < 2V)	-	-	V _{DD} ×0.2		
Output voltage 5 (COM0~7) (SEG00~49) (LCD mode is selected)	VOH5	1/3bias, IOH5=-0.02mA, V _{L1} =1.2V	V _{L3} -0.2	-	-		
	VOM5	1/3bias, IOM5=+0.02mA, V _{L1} =1.2V	-	-	V _{L2} +0.2		
	VOM5S	1/3bias, IOM5S=-0.02mA, V _{L1} =1.2V	V _{L2} -0.2	-	-		
	VOML5	1/3bias, IOML5=+0.02mA, V _{L1} =1.2V	-	-	V _{L1} +0.2		
	VOML5S	1/3bias, IOML5S=-0.02mA, V _{L1} =1.2V	V _{L1} -0.2	-	-		
	VOL5	1/3bias, IOL5=+0.02mA, V _{L1} =1.2V	-	-	0.2		
Output voltage 5 (COM0~7) (SEG00~49) (LCD mode is selected)	VOH5	1/2bias, IOH5=-0.01mA, V _{L1} =1.4V	V _{L3} -0.3	-	-		
	VOM5	1/2bias, IOM5=+0.01mA, V _{L1} =1.4V	-	-	V _{L2} +0.3		
	VOM5S	1/2bias, IOM5S=-0.01mA, V _{L1} =1.4V	V _{L2} -0.3	-	-		
	VOML5	1/2bias, IOML5=+0.01mA, V _{L1} =1.4V	-	-	V _{L1} +0.3		
	VOML5S	1/2bias, IOML5S=-0.01mA, V _{L1} =1.4V	V _{L1} -0.3	-	-		
	VOL5	1/2bias, IOL5=+0.01mA, V _{L1} =1.4V	-	-	0.3		

Output leak 1 (P00-P05, P20-P23, P30-P37, P40-P47, P50-P57, P60-P63, SWD,PUCTL)	IOOH1	VOH= V_{DD} (at high impedance)	-	-	+1	μA	3
	IOOL1	VOL= V_{SS} (at high impedance)	-1	-	-		

●DC characteristics (IIHL)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
Input current 1 (RESET_N)	I _{IH1}	V _{IH1} =V _{DD}	-	-	1	μA	4
	I _{IL1}	V _{IL1} =V _{SS}	-900	-300	-20		
Input current 3 (P00-P05, P20-P23, P30-P37, P40-P47, P50-P57, P60-P63, SWC, SWD, BRMP)	I _{IH3}	V _{IH3} =V _{DD} (at pull down)	1	15	200		
	I _{IL3}	V _{IL3} =V _{SS} (at pull up)	-200	-15	-1		
	I _{IH3Z}	V _{IH3} =V _{DD} (at high impedance)	-	-	1		
	I _{IL3Z}	V _{IL3} =V _{SS} (at high impedance)	-1	-	-		
Input current 4 (P36, P37, P40-P47, P50-P57, P60-P63)	I _{IH4Z}	V _{IH4} =5.0V (at high impedance)	-	-	1		

*1 : typ.rating is V_{DD}=3.0V, Ta=25°C

●DC characteristics (VIHL)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
Input voltage 1 (RESET_N, SWD, SWC, BRMP, P00-P05, P20-P23, P30-P37, P40-P47, P50-P57, P60-P63)	V _{IH1}	-	0.7 ×V _{DD}	-	V _{DD}	V	5
	V _{IL1}	-	0	-	0.3 ×V _{DD}		
Input terminal capacitance (RESET_N, SWD, SWC, BRMP, P00-P05, P20-P23, P30-P37, P40-P47, P50-P57, P60-P63)	C _{IN}	f=10kHz V _{rms} =50mV Ta=25°C	-	-	10	pF	-

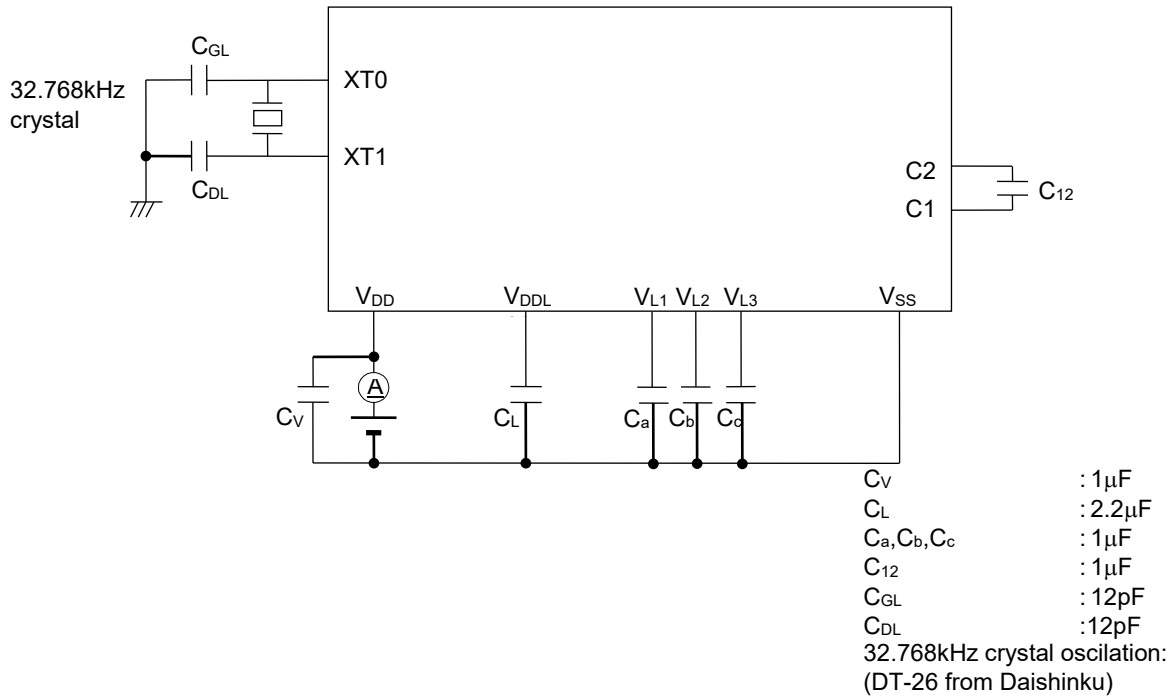
●DC characteristics (USB)

(V_{DD}=3.0 to 3.6V, V_{SS}=0V, T_a=-40 to +85°C, unless otherwise specified)

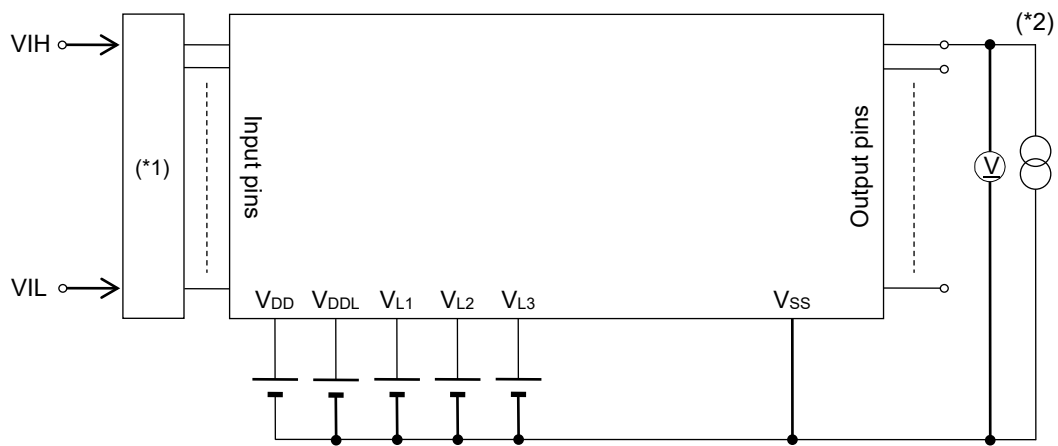
Parameter	Symbol	Condition	Rating*1			Unit	Measuring circuit
			Min.	Typ.	Max.		
Differential input sensitivity	V _{DI}	Absolute value of the difference between the DP and DM pins	0.2	-	-	V	
Differential common mode range	V _{CM}	Includes VDI range	0.8	-	2.5	V	
Single end input threshold voltage	V _{SE}	-	0.8	-	2.0	V	
High level output voltage	V _{OH}	15k W RL is connected to GND	2.8	-	-	V	
Low level output voltage	V _{OL}	1.5k W RL to 3.6 V	-	-	0.3	V	
Hi-Z state input/output leakage current	I _{LO}	0 V < V _{IN} < 3.3 V	-10		10	uA	
Driver output resistance	Z _{DRV}	Steady state	28		44	Ω	

●MEASURING CIRCUITS

MEASURING CIRCUIT 1



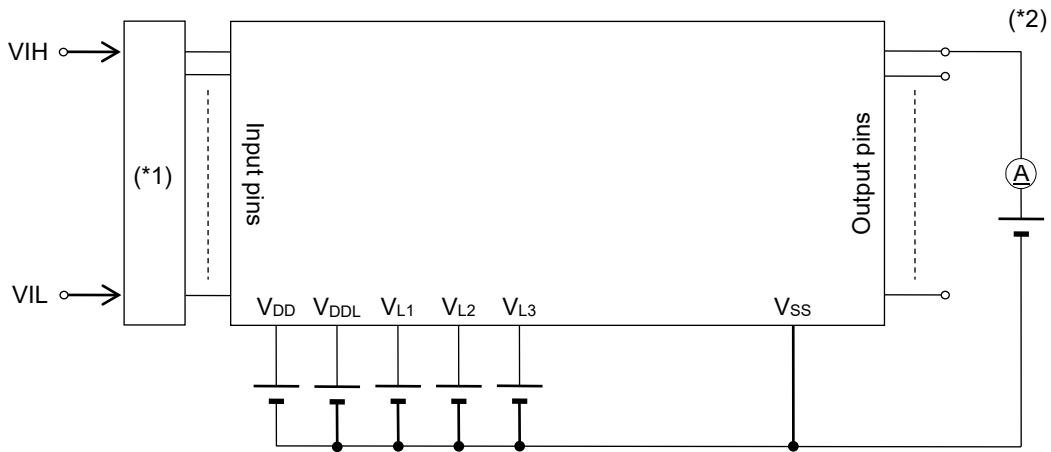
MEASURING CIRCUIT 2



(*1) Input logic circuit to determine the specified measuring conditions.

(*2) Measured at the specified output pins.

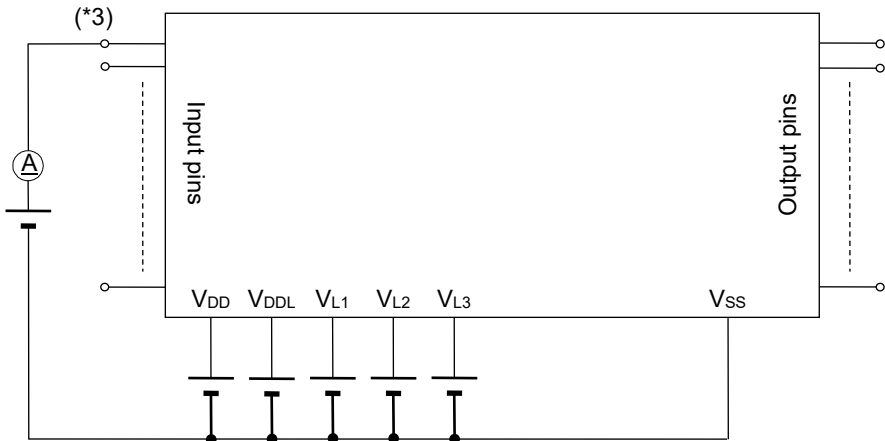
MEASURING CIRCUIT 3



*1: Input logic circuit to determine the specified measuring conditions.

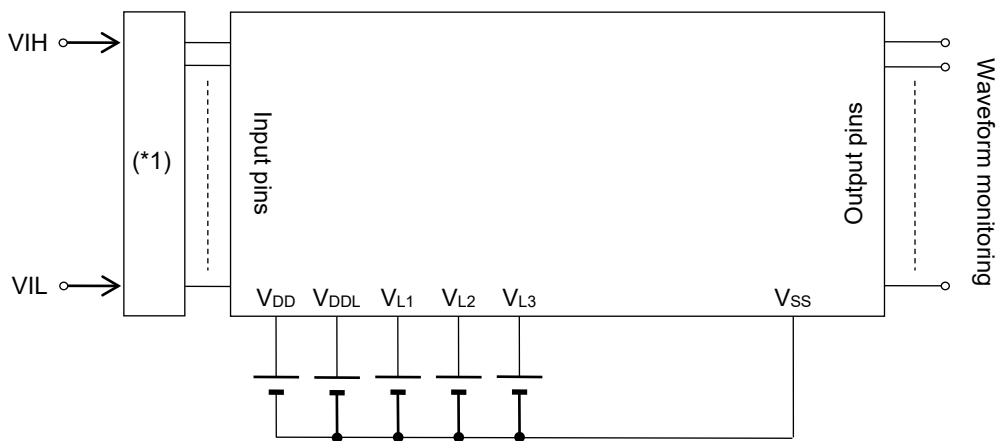
*2: Measured at the specified output pins.

MEASURING CIRCUIT 4



*3: Measured at the specified output pins.

MEASURING CIRCUIT 5



*1: Input logic circuit to determine the specified measuring conditions.

● AC characteristics (USB)

(V_{DD}=3.0 to 3.6V, V_{SS}=0V, T_a=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Applied pin
			Min.	Typ.	Max.		
Rise time (*1)	T _R	C _L = 50 pF	4	–	20	ns	DP, DM
Fall time (*1)	T _F	C _L = 50 pF	4	–	20	ns	
Output signal crossover voltage	V _{CRS}	C _L = 50 pF	0.8	–	2.5	V	
Data rate	T _{DRATE}	Average bit rate (12Mbps ±0.25%)	11.97	–	12.03	Mbps	

* 1: T_R and T_F: Rise time and fall time between 10% and 90% of the pulse amplitude, respectively

●AC characteristics (synchronous serial port)

($V_{DD}=1.8$ to $3.6V$, $V_{SS}=0V$, $T_a=-40$ to $+85^{\circ}C$, unless otherwise specified)

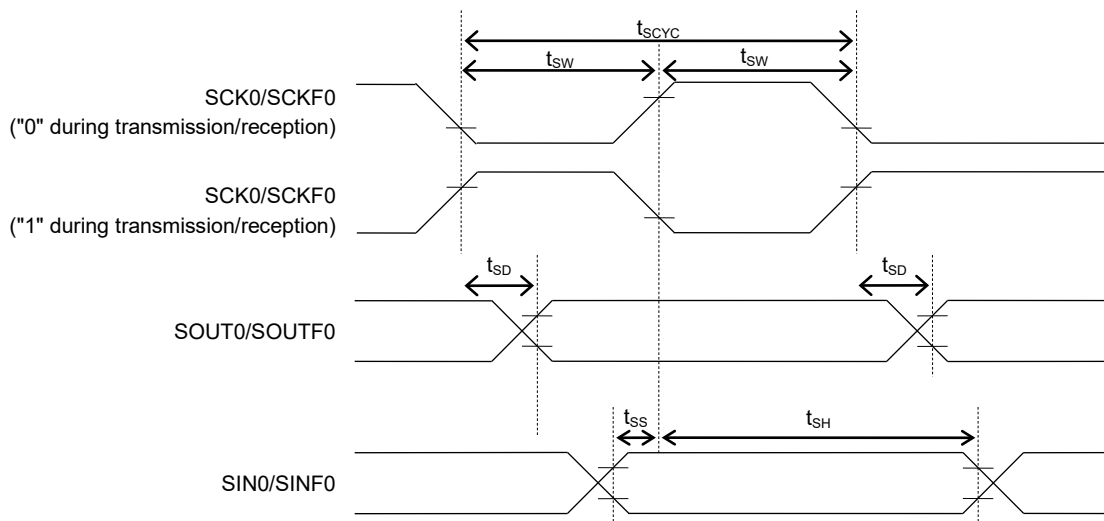
Parameter	Symbol	Conditon	Rating			Unit
			Min.	Typ.	Max.	
SCK input cycle (slave mode)	t_{scyc}	High-speed oscillation is not active	10	–	–	μs
		High-speed oscillation is active	500^{*2}	–	–	ns
SCK output cycle (master mode)	t_{scyc}	–	–	SCK ^{*1}	–	s
SCK input pulse width (slave mode)	t_{sw}	High-speed oscillation is not active	4	–	–	μs
		High-speed oscillation is active	200	–	–	ns
SCK output pulse width (master mode)	t_{sw}	–	t_{scyc} $\times 0.4$	t_{scyc} $\times 0.5$	t_{scyc} $\times 0.6$	s
SOUT output delay time (slave mode)	t_{sd}	–	–	–	180	ns
SOUT output delay time (master mode)	t_{sd}	–	–	–	80	ns
SIN input Setup time (slave mode)	t_{ss}	–	50	–	–	ns
SIN input Setup time (master mode)	t_{ss}	–	130	–	–	ns
SINinput Hold time	t_{sh}	–	50	–	–	Ns

*1 : The clock period which is selected by the below registers(min:250ns@ regularly, min:500ns@P02,P22 is used)

In case of SSIO : SOCK2-0 of serial port 0 mode register(SIO0MOD).

In case of SSIOF : SF0BR9-0 of SIOF0 port register(SF0BRR)

*2 : In case of SSIOF :Set the period of SYSCLK in half or less of the t_{scyc} in a period.



●AC characteristics (I²C Bus interface : Standard mode 100kHz)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

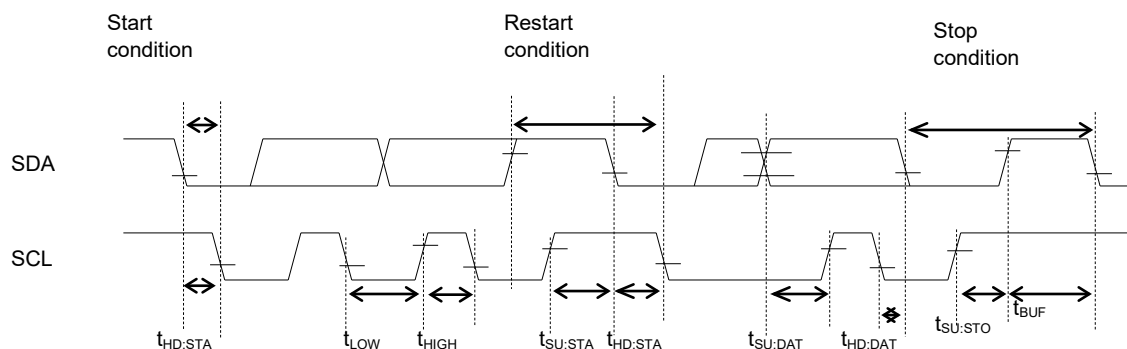
Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
SCL clock frequency	f _{SCL}	—	0	—	100	kHz
SCL hold time (Start/restart condition)	t _{HD:STA}	—	4.0	—	—	μs
SCL "L" level time	t _{LOW}	—	4.7	—	—	μs
SCL "H" level time	t _{HIGH}	—	4.0	—	—	μs
SCL setup time (restart condition)	t _{SU:STA}	—	4.7	—	—	μs
SDA setup time	t _{SU:DAT}	—	0.25	—	—	μs
SDA setup time (stop condition)	t _{SU:STO}	—	4.0	—	—	μs
Bus-free time	t _{BUF}	—	4.7	—	—	μs

●AC characteristics (I²C bus interface : fast mode 400kHz)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40 to +85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
SCL clock frequency	f _{SCL}	—	0	—	400	kHz
SCL hold time (start/restart condition)	t _{HD:STA}	—	0.6	—	—	μs
SCL "L" level time	t _{LOW}	—	1.3	—	—	μs
SCL "H" level time	t _{HIGH}	—	0.6	—	—	μs
SCL setup time (restart condition)	t _{SU:STA}	—	0.6	—	—	μs
SDA setup time	t _{SU:DAT}	—	0.1	—	—	μs
SDA setup time (stop condition)	t _{SU:STO}	—	0.6	—	—	μs
Bus-free time	t _{BUF}	—	1.3	—	—	μs

*1: Only at the time of SYSCLK=16MHz or 24MHz



● AC characteristics (RC-ADC)

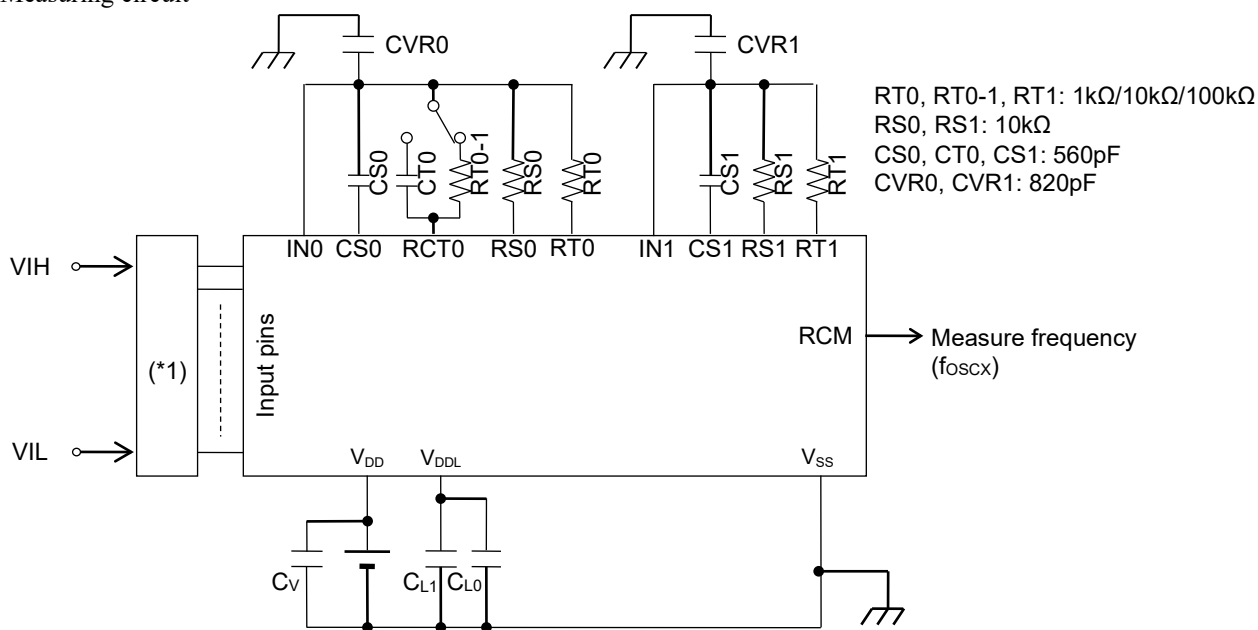
(V_{DD}=1.8 to 3.6V, V_{SS}=0V, T_a=-40~+85°C, unless otherwise specified)

Parameter	Symbol	Condition	Rating			unit
			Min.	Typ.	Max.	
Resister for oscillation	RS0,RS1,RT0, RT0-1,RT1	-	1	-	400	kΩ
Oscillation frequency V _{DD} = 3.0V CVR=820pF CS=560pF	f _{osc1_0}	Resister for oscillation =1kΩ	-	528	-	kHz
	f _{osc2_0}	Resister for oscillation =10kΩ	-	59	-	kHz
	f _{osc3_0}	Resister for oscillation =100kΩ	-	5.9	-	kHz
RS to RT oscillation frequency ratio *1 V _{DD} = 3.0V CVR=820pF CS=560pF	Kf1_0	RT0, RT0-1, RT1=1kΩ	8.225	8.94	9.655	-
	Kf2_0	RT0, RT0-1, RT1=10kΩ	0.99	1	1.01	-
	Kf3_0	RT0, RT0-1, RT1=100kΩ	0.093	0.101	0.109	-

*1: Kfx is the ratio of the oscillation frequency by the sensor resistor to the oscillation frequency by the reference resistor on the same conditions.

$$Kfx = \frac{f_{oscx} \text{ (RT0-CS0 oscillation)}}{f_{oscx} \text{ (RS0-CS0 oscillation)}} \quad , \quad \frac{f_{oscx} \text{ (RT0-1-CS0 oscillation)}}{f_{oscx} \text{ (RS0-CS0 oscillation)}} \quad , \quad \frac{f_{oscx} \text{ (RT1-CS1 oscillation)}}{f_{oscx} \text{ (RS1-CS1 oscillation)}} \quad (x = 1, 2, 3)$$

Measuring circuit



(*1) Input logic circuit to determine the specified measuring conditions.

[Note]

- Please have the shortest layout for the common node (wiring patterns which are connected to the external capacitors, resistors and IN0/IN1 pin), including CVR0/CVR1. Especially, do not have long wire between IN0/IN1 and RS0/RS1. The coupling capacitance on the wires may occur incorrect A/D conversion. Also, please do not have signals which may be a source of noise around the node.
- When RT0/RT1 (Thermistor and etc.) requires long wiring due to the restricted placement, please shield the signal by V_{SS}(GND).
- Please make wiring to components (capacitor, resistor and etc.) necessary for objective measurement. Wiring to reserved components may affect to the A/D conversion operation by noise the components itself may have.

●AC characteristics (Low speed clock output)

(V_{DD}=1.8 to 3.6V, V_{SS}=0V, Ta=-40~+85°C, unless otherwise specified)

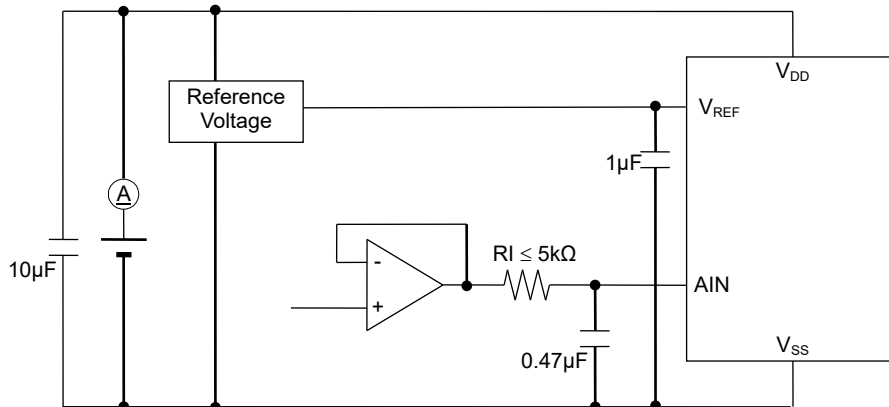
Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
Clock output frequency	clk	–	–	32.768	–	kHz

●Electrical Characteristics of SA-ADC

($V_{DD}=1.8$ to $3.6V$, $V_{SS}=0V$, $T_a=-40\sim+85^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit
			Min.	Typ.	Max.	
Resolution	n	—	—	12	—	bit
Integral non-linearity error	INL	$2.7V \leq V_{REF} \leq 3.6V$	-4	—	+4	LSB
		$2.2V \leq V_{REF} < 2.7V$	-6	—	+6	
		$1.8V \leq V_{REF} < 2.2V$ (using Low-speed clock)	-10	—	+10	
Differential non-linearity error	DNL	$2.7V \leq V_{REF} \leq 3.6V$	-3	—	+3	
		$2.2V \leq V_{REF} < 2.7V$	-5	—	+5	
		$1.8V \leq V_{REF} < 2.2V$ (using Low-speed clock)	-9	—	+9	
Zero-scale error	V_{OFF}	$2.2V \leq V_{REF} \leq 3.6V$	-6	—	+6	
		$1.8V \leq V_{REF} < 2.2V$ (using Low-speed clock)	-10	—	+10	
Full-scale error	FSE	$2.2V \leq V_{REF} \leq 3.6V$	-6	—	+6	
		$1.8V \leq V_{REF} < 2.2V$ (using Low-speed clock)	-10	—	+10	
Input impedance	RI	—	—	—	5k	Ω
Reference voltage	V_{REF}	—	1.8	—	V_{DD}	V
Conversion time	t_{CONV}	Using High-speed clock(max. 4MHz)	—	170	—	clk
		Using Low-speed clock	—	16	—	

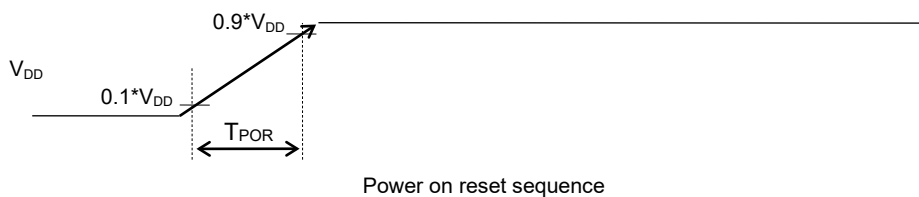
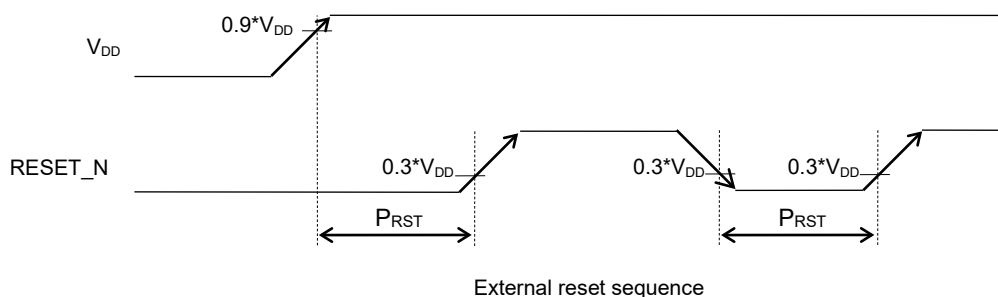
Measuring circuit



●Reset characteristics

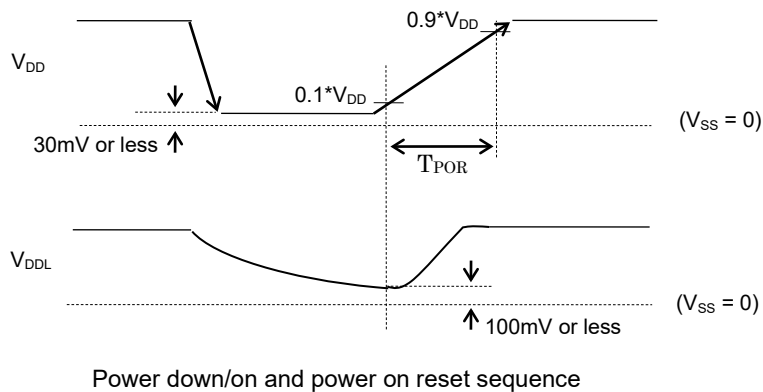
($V_{DD}=1.8$ to $3.6V$, $V_{SS}=0V$, $T_a=-40$ to $+85^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Condition	Rating			Unit	Measuring circuit
			Min.	Typ.	Max.		
Reset pulse width	P_{RST}	-	200	-	-	μs	1
Reset noise elimination pulse width	P_{NRST}	-	-	-	0.3	μs	
Power-on reset activation power rise time	T_{POR}	-	-	-	10	ms	



●Power-on and shutdown Procedures

In case of power-on or shutdown of V_{DD} , the procedures and constraints are shown as following.

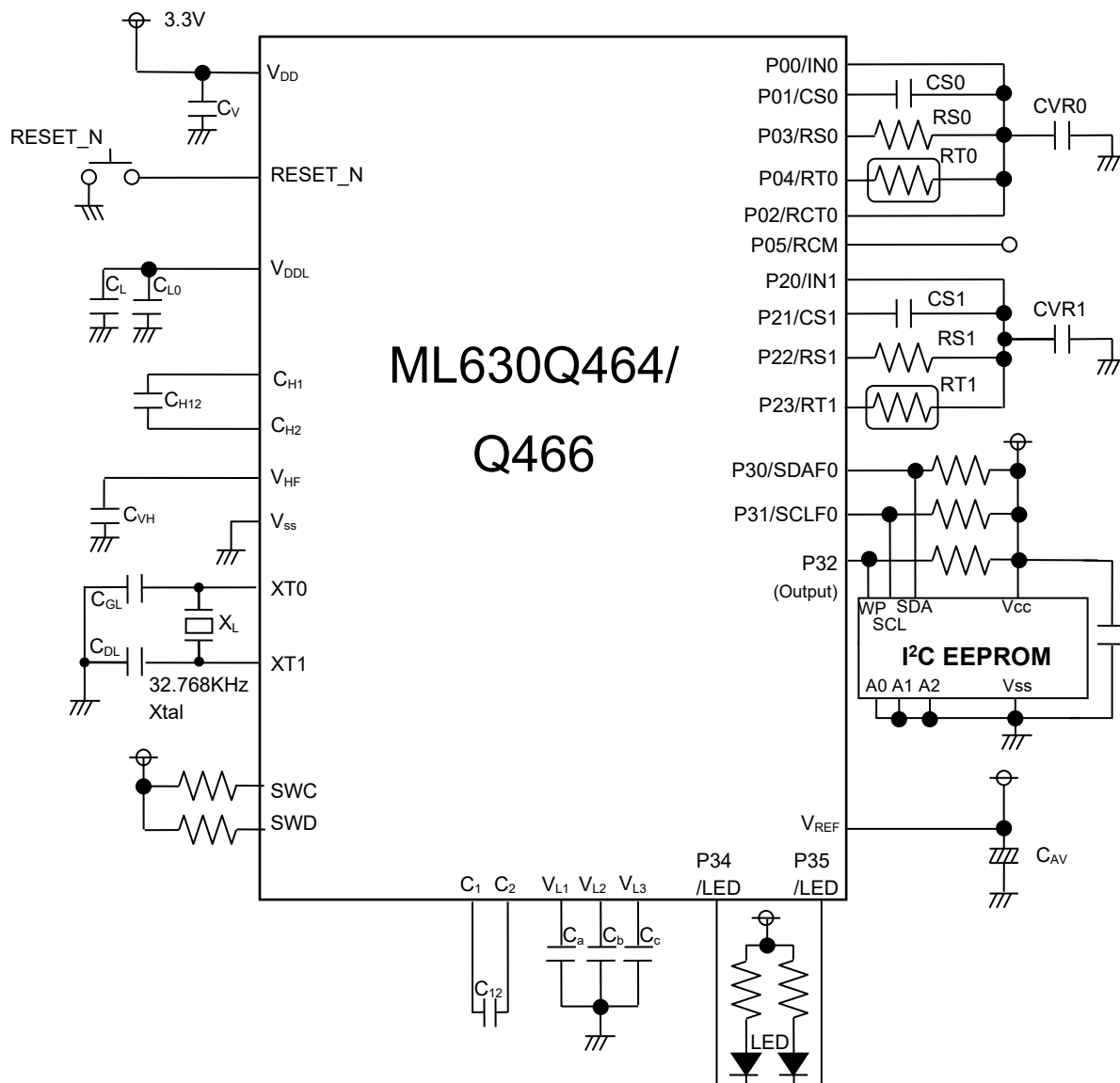


Note:

If V_{DDL} level is 100mV or more over, reset the IC by RESET_N pin after power-on.

T_{POR} is the value when V_{DD} slope is linear. If V_{DD} slope is not linear in your system, use RESET_N or contact us.

■ APPLICATION CIRCUIT EXAMPLE



Cv	: 1uF*		
CL	: 2.2uF	CL0	: open*
CGL,CdL	: 12 to 16pF*		
Ca~Cc	: 1uF*	C12	: 1uF*
CH12	: 1uF*	CVH	: 1uF*
CAV	: 1uF*	RS0, RS1	: 10 KΩ
CS0, CS1	: 560 pF	CVR0, CVR1	: 820 pF
RT0, RT1	: Thermistor (103AT/Semitec)		
XL	: DT-26, Daishinku		

*: Make a decision the parameters after evaluating on user's conditions when designing circuits for mass production.

■ PACKAGE DIMENSIONS

● ML630Q464/Q466 Package Dimensions

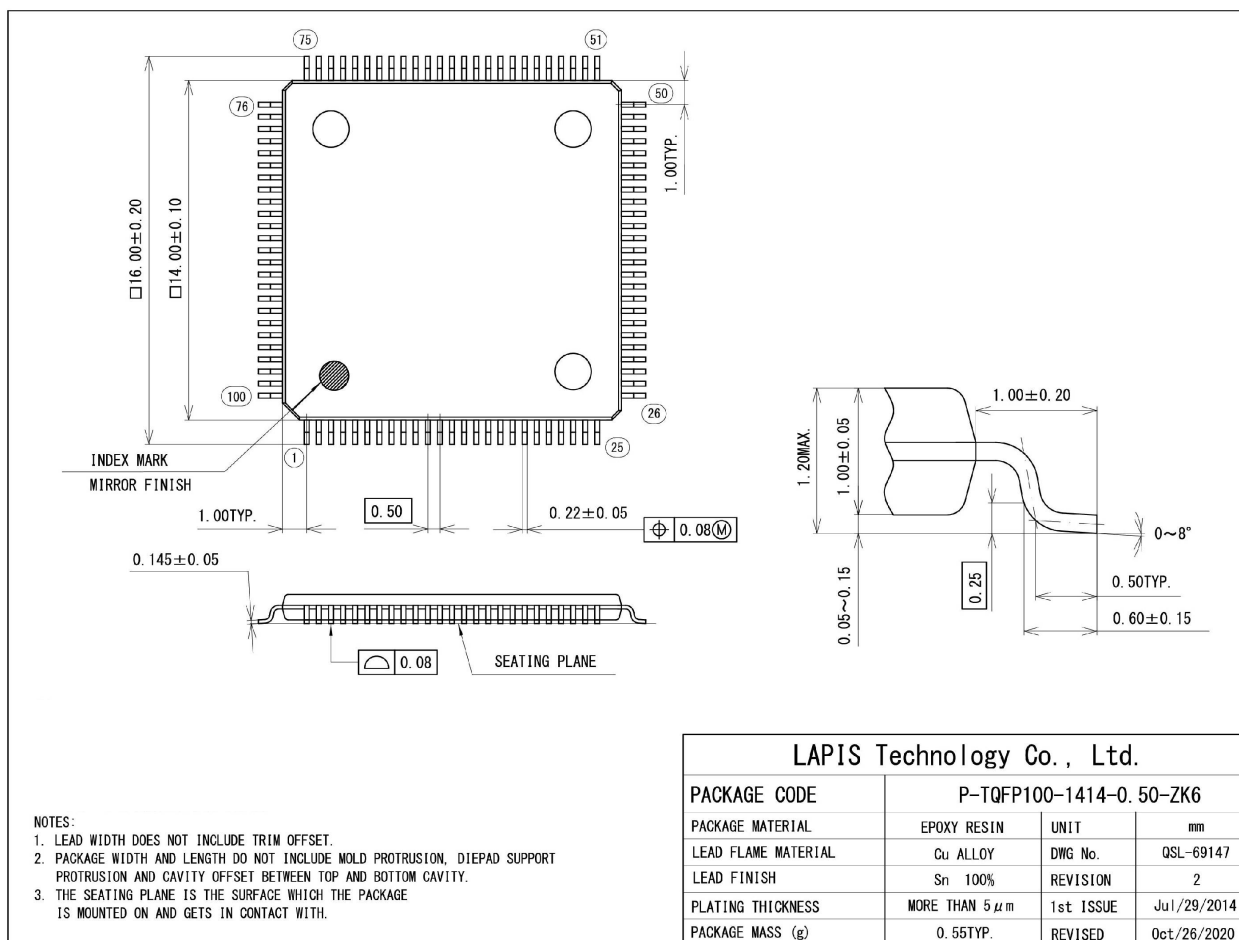


Figure B-1 TQFP100

Notes for Mounting the Surface Mount Type Package

The surface mount type packages are very susceptible to heat in reflow and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact a ROHM sales office for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

■ REVISION HISTORY

Document No.	Date	Page		Description
		Previous Edition	Current Edition	
FEDL630Q464-01	Oct. 26. 2016	-	-	Final Edition
FEDL630Q464-02	May. 13. 2021	12	12	Updated about RESET_N and BRMP pins
		14	14	Added comment in recommended operating conditions.
		28	28	Added comment
		33	33	Corrected "Power-on and shutdown Procedures"
		16	33	Changed placement of reset characteristics. Added note.
		*	*	Corrected typo
FEDL630Q464-03	Dec. 15. 2023	1	1	Added application information.
		35	35	Updated Figure B-1.
		-	37	Added Notes for product usage.
		37	38	Revised the Note.

Notes for product usage

Notes on this page are applicable to the all microcontroller products.

For individual notes on each LAPIS Technology microcontroller product, refer to [Note] in the chapters of each user's manual.

The individual notes of each user's manual take priority over those contents in this page if they are different.

1. HANDLING OF UNUSED INPUT PINS

Fix the unused input pins to the power pin or GND to prevent to cause the device performing wrong operation or increasing the current consumption due to noise, etc. If the handlings for the unused pins are described in the chapters, follow the instruction.

2. STATE AT POWER ON

At the power on, the data in the internal registers and output of the ports are undefined until the power supply voltage reaches to the recommended operating condition and "L" level is input to the reset pin.

On LAPIS Technology microcontroller products that have the power on reset function, the data in the internal registers and output of the ports are undefined until the power on reset is generated.

Be careful to design the application system does not work incorrectly due to the undefined data of internal registers and output of the ports.

3. ACCESS TO UNUSED MEMORY

If reading from unused address area or writing to unused address area of the memory, the operations are not guaranteed.

4. CHARACTERISTICS DIFFERENCE BETWEEN THE PRODUCTS

Electrical characteristics, noise tolerance, noise radiation amount, and the other characteristics are different from each microcontroller product.

When replacing from other product to LAPIS Technology microcontroller products, please evaluate enough the apparatus/system which implemented LAPIS Technology microcontroller products.

5. USE ENVIRONMENT

When using this product in a high humidity environment and an environment where dew condensation, take moisture-proof measures.

Notes

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2-4-8 Shinyokohama, Kouhoku-ku, Yokohama 222-8575, Japan

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